

# Vector Modulator/Mixer

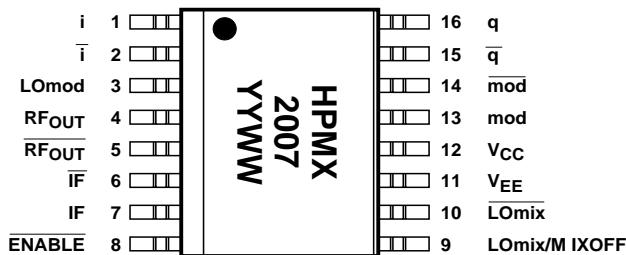
## Technical Data

**HPMX-2007**

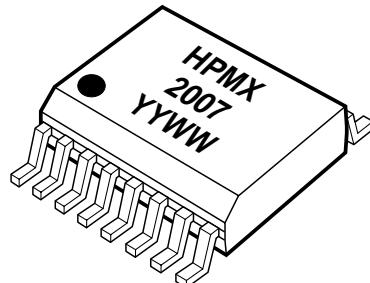
### Features

- 5 MHz to 4 GHz Overall Operating Frequency Range
- 40-400 MHz LOmod range
- 2.7 - 5.5 V Operation (3 V, 25 mA)
- Differential High Impedance i, q Inputs
- On-Chip Linear RC Phase Shifter
- -23 dBm Modulator S.E. Output Power into  $50\ \Omega$  at 150 MHz
- -15 dBm Linear (-11 dBm Saturated) Mixer Output Power into  $50\ \Omega$  at 1900 MHz
- Mixer Can Be Used for Up/Down Conversion or Disabled (3 V, 10 mA)
- Standby Mode ( $<1\ \mu A$ )
- JEDEC Standard SSOP-16 Surface Mount Package

### Package Pin Configuration



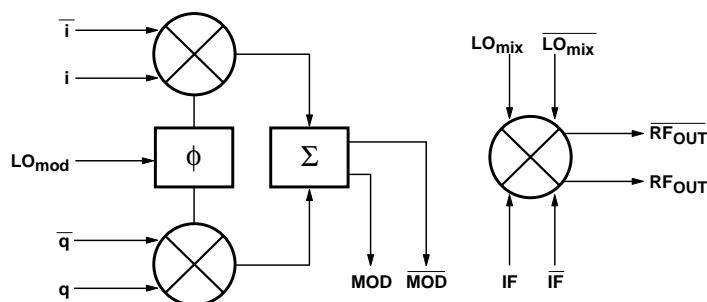
### Plastic SSOP-16



### Applications

- NADC, PDC, GSM Handsets and Base Stations
- PCS Handsets and Base Stations
- DLMR Handsets
- CDPD Radios
- ISM Band Wireless Links

### Functional Block Diagram



### General Description

The HPMX-2007 vector modulator/mixer IC is designed to meet the needs of cellular and PCS telephone applications.

The heart of the IC is a vector (or quadrature) modulator followed by a Gilbert cell mixer. The modulator and mixer can be used together, drawing only 25 mA from a 3.0 volt supply. The mixer can be disabled by connecting either LOmix or LOmix to V<sub>CC</sub>,

allowing operation of the modulator alone and reducing current drain to only 10 mA.

The i and q signal inputs are balanced to insure high common mode noise rejection.

The output of the mixer is a differential pair of open collectors.

One collector can be connected to  $V_{CC}$  and the other matched to  $50 \Omega$  using a shunt L, series C network. Alternatively, the output can be matched to  $50 \Omega$  through a 4:1 balun.

The SSOP-16 package insures that the IC occupies a minimal amount of printed circuit board space.

The HPMX-2007 is manufactured using Agilent Technologies's 30 GHz ISOSAT-II process which combines stepper lithography, self alignment, ion implantation techniques and gold metallization to produce state-of-the-art RFICs.

### **HPMX-2007 Absolute Maximum Ratings<sup>[1]</sup>**

Recommended Operating Range of  $V_{CC} = 2.7$  to  $5.5$  V,  $T_A = -40$  to  $+85^\circ\text{C}$ .

Parameter	Min.	Max.
$V_{CC}$ Supply Voltage		8 V
Power Dissipation <sup>[2,3]</sup>		400 mW
RF Input Power		+15 dBm
Junction Temperature		+150°C
Storage Temperature	-65°C	+150°C

#### **Thermal Resistance:<sup>[2]</sup>**

$$\theta_{JC} = 150^\circ\text{C/W}$$

#### **Notes:**

1. Operation of this device in excess of any of these parameters may cause permanent damage.
2.  $T_{case} = 25^\circ\text{C}$ .
3. Derate at 7 mW/ $^\circ\text{C}$  for  $T_{case} > 90^\circ\text{C}$ .

### **Standard Test Conditions**

Unless otherwise stated, all test data was taken on packaged parts under the following conditions:

$V_{CC} = +3.0$  VDC,  $Z_{out} = 50 \Omega$ , ambient temperature  $T_A = 25^\circ\text{C}$

LOmod input: 149.67 MHz, 400 mV<sub>p-p</sub>, single ended

LOmix input: 1750.33 MHz, -10 dBm, single ended,  $50 \Omega$

Single sideband tests:

i, q input: 10 kHz, 600 mV<sub>p-p</sub> differential with  $V_{CC}/2 = 1.5$  V offset.

See Figure 25 for test setup schematic diagram.

### **HPMX-2007 Key Guaranteed Electrical Specifications**

Standard test conditions apply unless otherwise noted.

Symbol	Parameters and Test Conditions	Min.	Typ.	Max.	Units
$P_{out}$	SSB Output Power	-17.5	-15		dBm
	Unwanted Sideband Output Level in SSB Mode		-40	-30	dBc
	LOmix + LOmod Leakage Relative to SSB Output Power		-35	-27	dBc
$I_d$	Device Current ( $\overline{\text{ENABLE}}$ Open)		25	30	mA
	Device Current, Disabled Mode ( $\overline{\text{ENABLE}} = V_{CC}$ )		5	25	$\mu\text{A}$

## HPMX-2007 Summary Characterization Information

Standard test conditions apply unless otherwise noted.

<b>Modulator-Only Mode</b>	<b>Typ</b>	<b>Units</b>
DC Current Drain	10	mA
i, q Input 3 dB Bandwidth	>90	MHz
LOmod Input Frequency Range (for Sideband Suppression > 30 dBc)	40-400	MHz
SSB Output Current (Open Collectors). See Figure 26.	2	mA pk-pk diff.
SSB LOmod Suppression @ 150 MHz	-35	dBc
DSB 3rd Order IM Products @ 150 MHz	-45	dBc
Output Noise Floor	-160	dBm/Hz

<b>Modulator + Mixer Performance (Output at 1900 MHz)</b>	<b>Typ</b>	<b>Units</b>
Total DC Current Drain (Mixer Cannot Be Used Without Also Turning On the Modulator)	25	mA
Mixer IF Input 3 dB Bandwidth	400	MHz
Differential Output Current (Open Collectors). See Figure 26.	12	mA pk-pk diff.
Linear Output Power. See Figure 25.	-15	dBm
IM <sub>3</sub> Output Power. See Figure 19.	-22	dBc
Output Noise Floor	-153	dBm/Hz
LOmix Leakage to RF Output	-22	dBc

## HPMX-2007 Pin Description Table

No.	Mnemonic	Description	Typical Signal
1	i	Balanced modulation input Z = 75 kΩ    0.5 pF	600 mV pk-pk differential average value of V <sub>CC</sub> /2
2	̄i		
3	LOmod	Modulator LO input Z = 5 kΩ    0.5 pF	40-400 MHz, -10 dBm from 50 Ω source
4	RF	Balanced mixer RF output open collectors Z = current src.    3 kΩ    0.7 pF	5-4000 MHz, 12 mA pk-pk differential, with network shown in Figure 25. Should be connected to V <sub>CC</sub> when mixer is not used.
5	̄RF		
6	IF	Balanced mixer input Z = 5 kΩ    0.5 pF	40-400 MHz, 350 mV pk-pk diff.
7	IF		
8	ENABLE	Chip enable input	3 V CMOS logic compatible
9	LOmix/mixoff	Balanced mixer LO input and mixer enable line Z = 1 kΩ    0.6 pF	-10 dBm from 50 Ω source network shown in Figure 25. Should be con- nected to V <sub>CC</sub> when mixer is not used.
10	̄LŌ1		
11	V <sub>EE</sub>	Chip substrate connection	0 V (DC and AC ground)
12	V <sub>CC</sub>	Power supply connection	+2.7 - 5.5 V
13	MOD	Balanced modulator RF output open collectors Z = current src.    35 kΩ    0.7 pF	40-400 MHz, 2 mA pk-pk differential with network shown in Figure 25.
14	̄MOD		
15	̄q	Balanced modulation input Z = 75 kΩ    0.5 pF	600 mV pk-pk differential average value of V <sub>CC</sub> /2
16	q		

**Note:** Impedances shown are AC equivalents at each pin, relative to ground. See Figure 26.

**Table 1. Typical Output Spurs.**

All values in dBc relative to output at 1900 MHz.  $f_{LOmix} = 1750.33$  MHz,  $f_{LOmod} = 149.67$  MHz,  $V_i = V_q = 1.65$  V,  $V_i = V_q = 1.35$  V,  $f_{spur} = m^*f_{LOmix} + n^*f_{LOmod}$

$m \downarrow n \rightarrow$	-6	-5	-4	-3	-2	-1	0	1	2	3	4	5	6
0	-38.8	-53.4	-47.7	-60.1	-46.7	-72.3	-	-72.2	-46.7	-60.1	-47.6	-53.3	-38.8
1	-51.9	-37.3	-37.7	-23.9	-23.6	0	-21.4	0	-22.1	-17.7	-41.7	-28.7	-35.1
2	-26.6	-32.8	-23.7	-36.3	-16.5	-34.5	-19.5	-21.3	-26.3	-36.8	-29.5	-48.8	-40.6
3	-37.8	-32.7	-57.4	-28.3	-25.9	-21.2	-27.5	-23.8	-38.7	-45.9	-54.3	-41.2	-48.8
4	-45.7	-47.1	-45.3	-47.0	-39.4	-51.1	-43.3	-40.4	-49.7	-54.7	-49.8	-57.8	-57.2
5	-65.0	-67.5	-56.1	-61.7	-57.6	-52.0	-43.5	-54.8	-61.6	-65.4	-59.9	-64.7	-63.7
6	-65.5	-82.2	-65.9	-60.7	-57.4	-62.7	-57.5	-66.2	-64.9	-77.1	-72.0	-83.1	-86.3

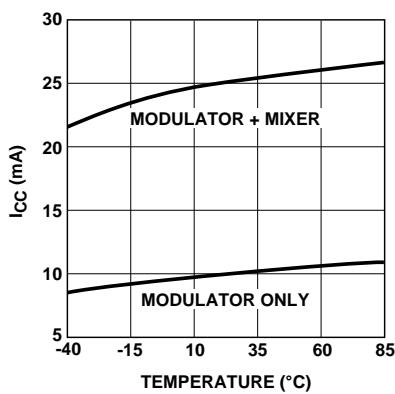


Figure 1.  $I_{CC}$  vs. Temperature.

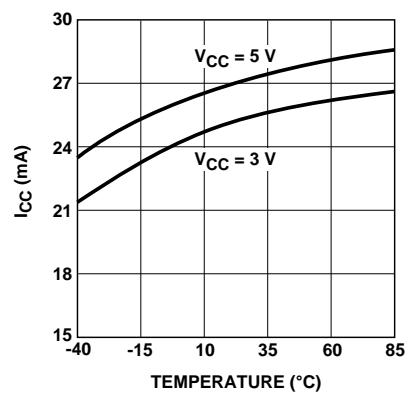


Figure 2. Modulator + Mixer  $I_{CC}$  vs. Temperature and  $V_{CC}$ .

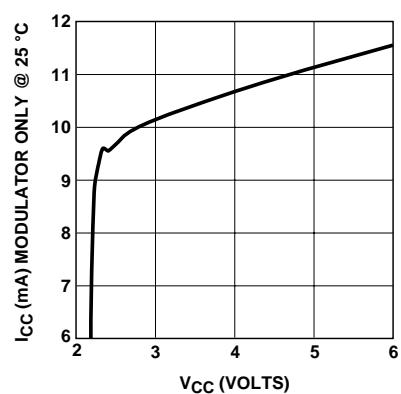


Figure 3. Modulator Only Mode  $I_{CC}$  vs.  $V_{CC}$  at  $25^{\circ}\text{C}$ .

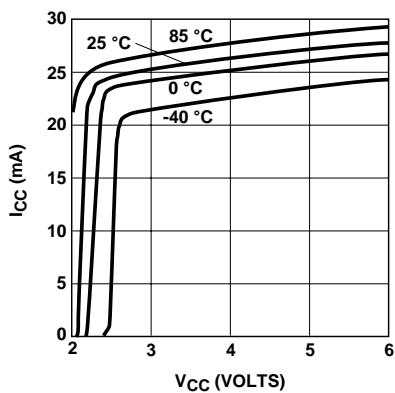


Figure 4. Modulator + Mixer  $I_{CC}$  vs.  $V_{CC}$  and Temperature.

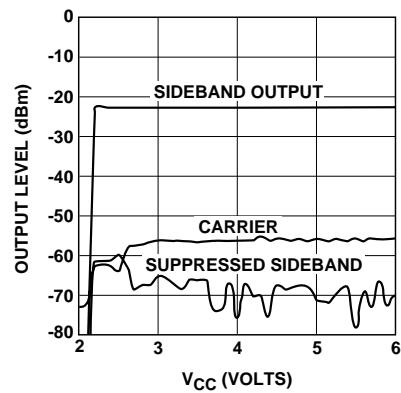


Figure 5. Modulator Only SSB Performance vs.  $V_{CC}$ .

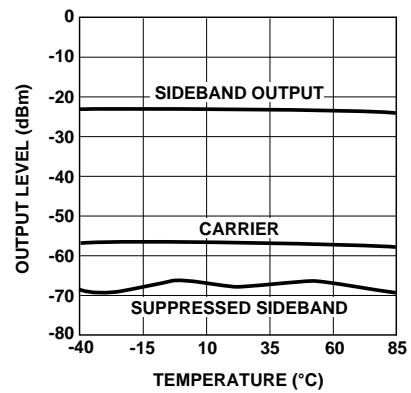
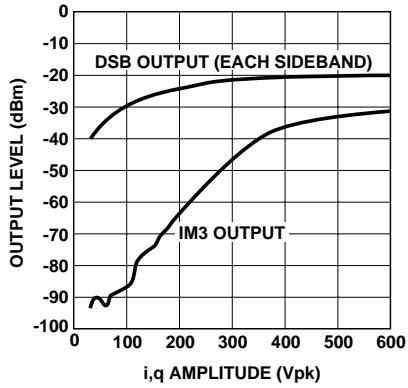
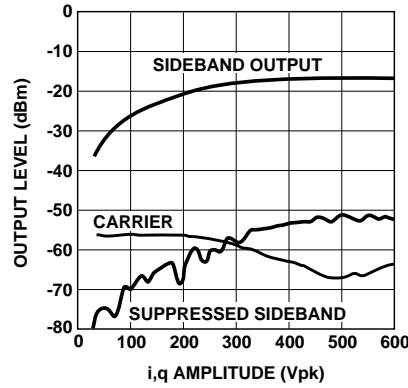


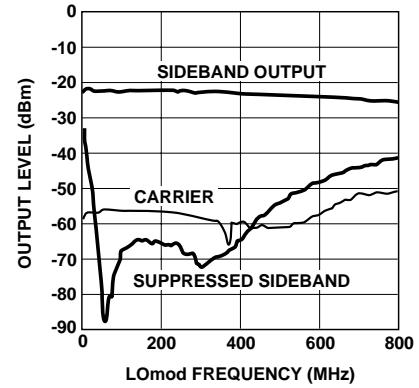
Figure 6. Modulator Only SSB Performance vs. Temperature.



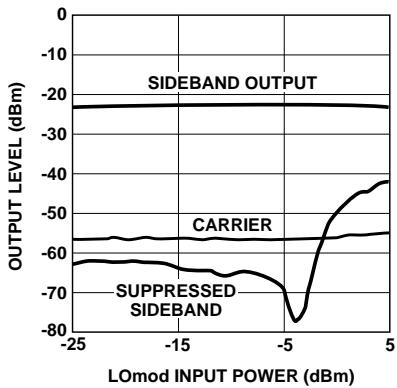
**Figure 7. Modulator Only DSB Output Power Level and IM3 Level vs. i,q Input Amplitude (Each Pin, Relative to Ground).**



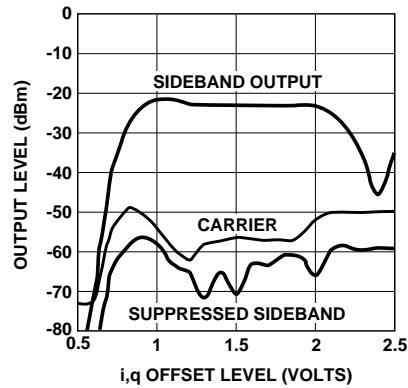
**Figure 8. Modulator Only SSB Mode Performance vs. i,q Input Amplitude (Each Pin, Relative to Ground).**



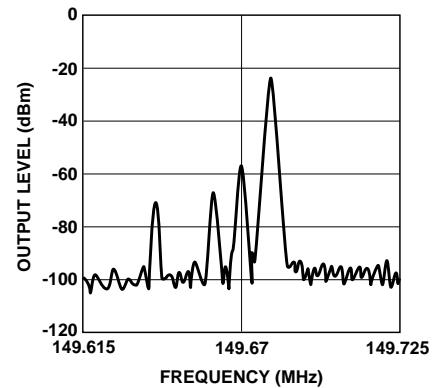
**Figure 9. Modulator Only SSB Output Power, Carrier and Sideband Suppression vs. LOmod Frequency.**



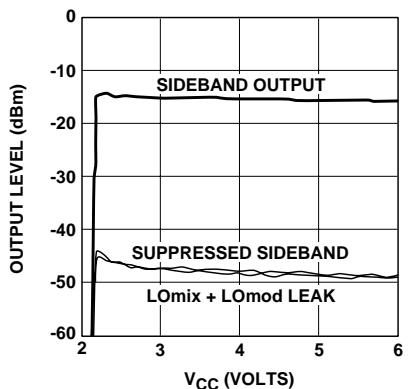
**Figure 10. Modulator Only SSB Performance vs. LOmod Input Level.**



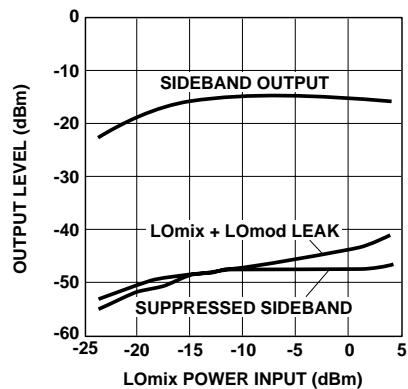
**Figure 11. Modulator Only SSB Performance vs. i,q Offset Level (Each Pin, Relative to Ground).**



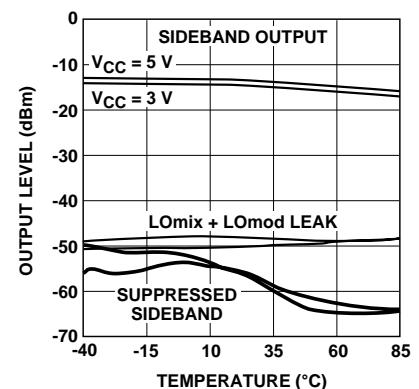
**Figure 12. Modulator Only SSB Output Spectrum at 150 MHz.**



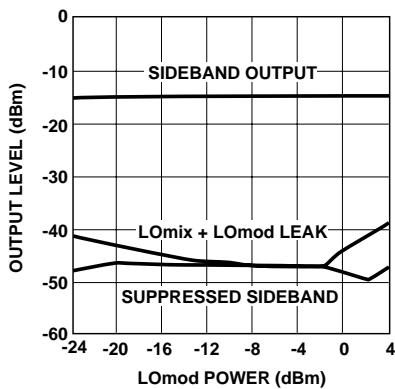
**Figure 13. Modulator + Mixer SSB Output Levels vs. V<sub>CC</sub>.**



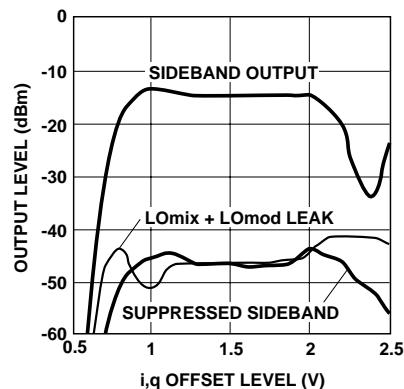
**Figure 14. Modulator + Mixer SSB Output Levels vs. LOmix Power Input.**



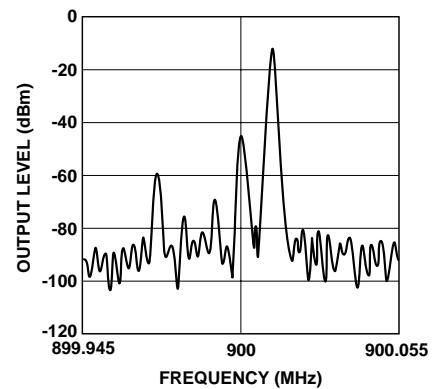
**Figure 15. Modulator + Mixer SSB Output Levels vs. Temperature and V<sub>CC</sub>.**



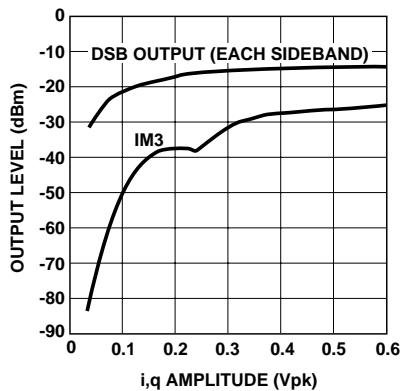
**Figure 16.** Modulator + Mixer SSB Output Levels vs. LOmod Power Input.



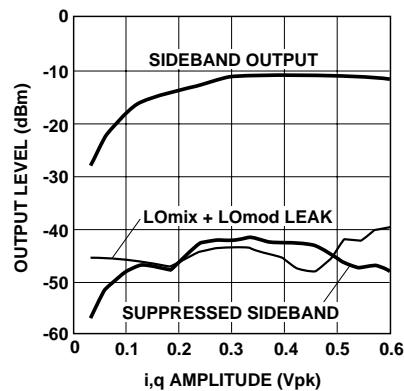
**Figure 17.** Modulator + Mixer SSB Performance vs. i,q Offset Level (Each Pin, Referenced to Ground).



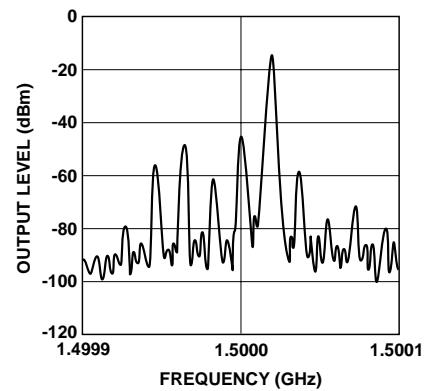
**Figure 18.** Modulator + Mixer SSB Output Spectrum at 900 MHz.



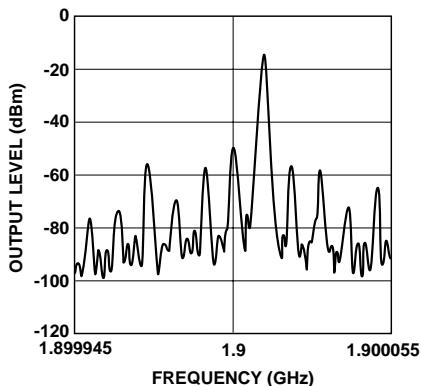
**Figure 19.** Modulator + Mixer DSB Performance vs. i,q Amplitude (Each Pin, Referenced to Ground).



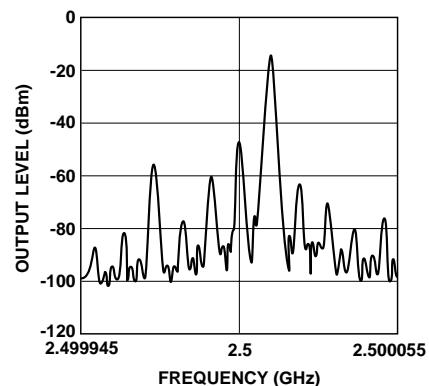
**Figure 20.** Modulator + Mixer SSB Performance vs. i,q Input Amplitude (Each Pin, Referenced to Ground).



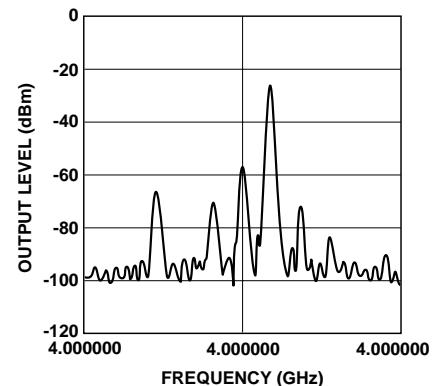
**Figure 21.** Modulator + Mixer SSB Output Spectrum at 1500 MHz.



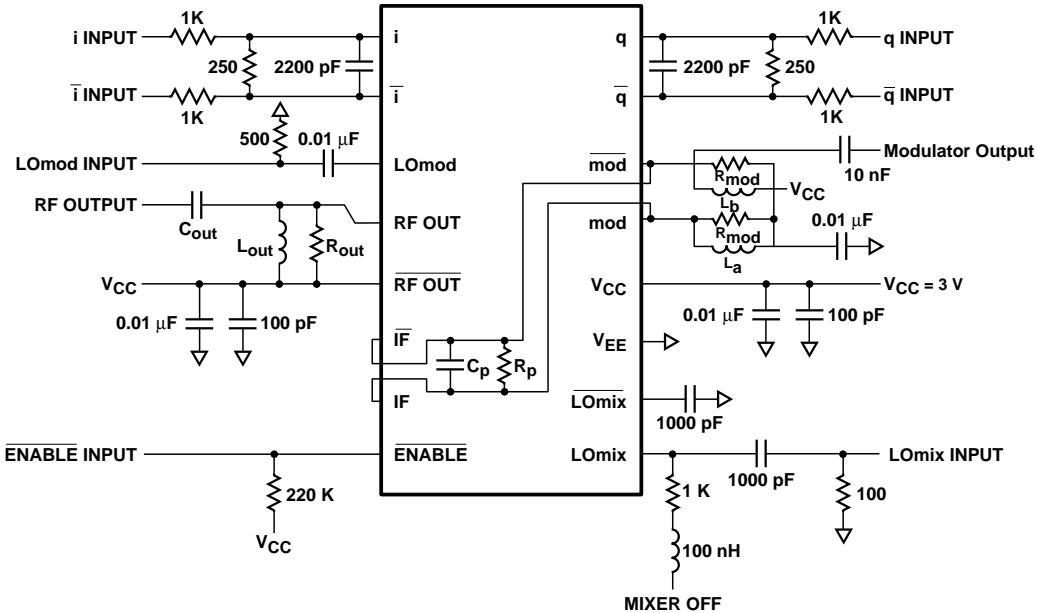
**Figure 22.** Modulator + Mixer SSB Output Spectrum at 1900 MHz.



**Figure 23.** Modulator + Mixer SSB Output Spectrum at 2500 MHz.



**Figure 24.** Modulator + Mixer SSB Output Spectrum at 4000 MHz.



**Figure 25.** Test Board Schematic Diagram. Connecting the Mixer Off Line to +3 V Turns Off the Mixer. Leave It Open to Allow Mixer to Operate. Component Values that Change with Frequency Are Shown in Table 2.

**Table 2.** Test Board Component Values that Change with Operating Frequency. Refer to Figure 25.

$f_{LOmix} + f_{LOmod}$ MHz	$f_{LOmix}$ MHz	$f_{LOmod}$ MHz	$R_{mod}$ $\Omega$	$L_a$ nH	$L_b$ nH	$R_p$ $\Omega$	$C_p$ pF	$C_{mod}$ nF	$R_{out}$ $\Omega$	$L_{out}$ nH	$C_{out}$ pF
900	750.33	149.67	-	100	100	430	3.9		200	12	3.3
1500	1350.33	149.67	-	100	100	300	3.9		120	5.6	1.8
1900	1750.33	149.67	-	100	100	430	3.9		120	3.3	1.2
2500	2350.33	149.67	-	100	100	430	3.9		75	-	-
mod. only	-	149.67	300	0	-	-	-	10	0	-	-

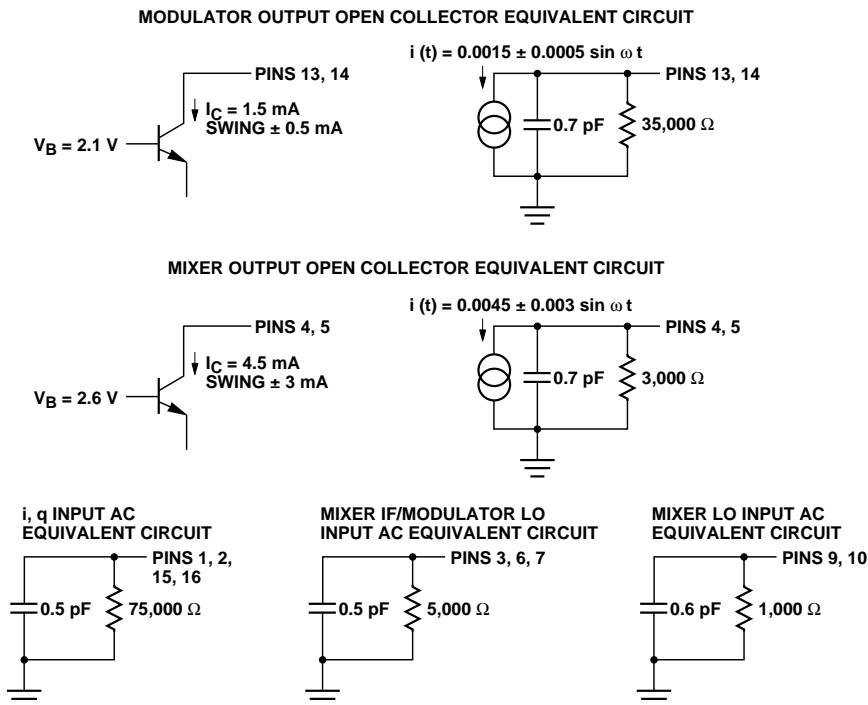


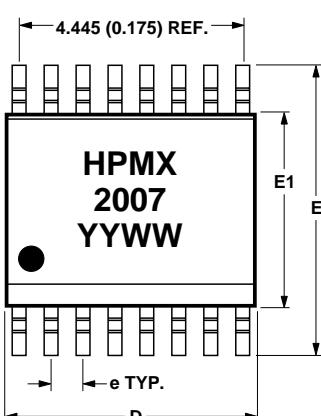
Figure 26. Equivalent Circuits for HPMX-2007 Inputs/Outputs.

### Part Number Ordering Information

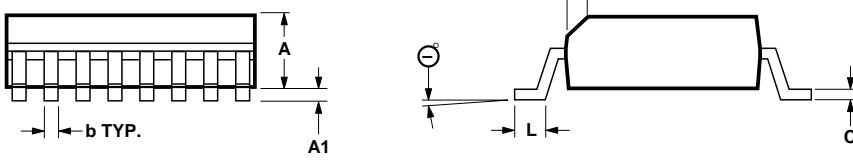
Part Number	No. of Devices	Container
HPMX-2007-BLK	25	Tape
HPMX-2007-TR1	1000	Tape and Reel

### Package Dimensions

JEDEC Standard SSOP-16 Package



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.372 (0.054)	1.575 (0.062)
A1	0.127 (0.005)	0.254 (0.010)
b	0.203 (0.008)	0.305 (0.012)
C	0.178 (0.007)	0.254 (0.010)
D	4.801 (0.189)	5.004 (0.197)
E	5.867 (0.231)	6.121 (0.241)
e	0.635 BSC (0.025)	
E1	3.835 (0.151)	3.988 (0.157)
h	0.305 (0.012)	0.457 (0.018)
L	0.533 (0.021)	0.787 (0.031)
θ	0	8



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Obsoletes 5965-7239E  
5968-1787E (11/99)